Name of the part	Pb	Cd	Hg	Cr-VI	PBB	PBDE
Die	O	O	O	O	O	O
Lead Frame	O	O	O	O	O	O
Mould Compound	O	O	O	O	O	O
Post-plating	O	O	O	O	O	O
Solder Wire	X	O	O	O	O	O
Wire	O	O	O	O	O	O

O: Indicates all homogeneous materials` hazardous substances content are below the SJ/T11363-2006 limit.

X: Indicates that the hazardous substance content contained in any one of the homogenuous materials of the part exceeded the MCV limits specified in the Standard SJ/T 11363-2006.

Remark: All WeEn Semiconductors products have an environmental friendly use period (EFUP) of 50 years.

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